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(54) Title: PLASMA PROCESSING APPARATUS

(57) Abstract: Disclosed is a plasma processing apparatus including a processing chamber and a workpiece support disposed in the processing chamber configured to support a workpiece during processing. The apparatus includes a hollow cathode disposed in the processing chamber that is configured to produce a plasma in the processing chamber. The hollow cathode is disposed adjacent to a perimeter of the workpiece support and the workpiece. The apparatus includes a gas distribution system configured to provide process gas to the processing chamber. Methods for processing workpieces are also disclosed.

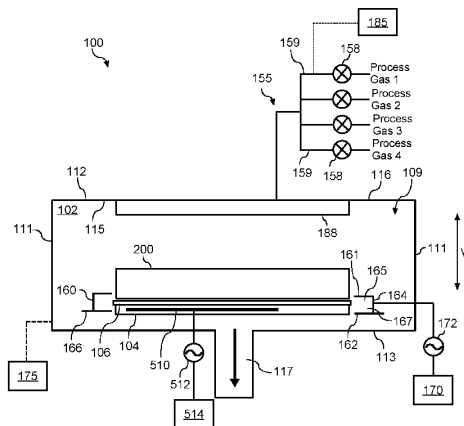


FIG. 1

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